

2 a first circuitized substrate having at least one conductive aperture therein having an  
3 external surface;

4 a second circuitized substrate having at least one conductive aperture therein having  
5 an external surface, said first and second circuitized substrates aligned such that said at least one  
6 conductive aperture of said first circuitized substrate is substantially aligned with said at least one  
7 conductive aperture of said second circuitized substrate, said at least one conductive aperture of  
8 said first circuitized substrate and said at least one conductive aperture of said second circuitized  
9 substrate including a conductive metallic layer thereon selected from the group consisting of  
10 copper, nickel, gold, chromium, solder and alloys thereof ; and

11 at least one solder member including a first contact portion extending from said  
12 external surface of said conductive aperture of said first circuitized substrate, said first contact  
13 portion including a cross-sectional configuration that is substantially oval or ellipsoidal, and a  
14 second contact portion extending substantially within both of said aligned conductive apertures  
15 of said first and second circuitized substrates to secure said circuitized substrates together, said  
16 metallic material of said at least one conductive aperture of said first circuitized substrate and  
17 said at least one conductive aperture of said second circuitized substrate including a protective  
18 layer thereon, said protective layer selected from the group consisting of benzotriazole, chlorite,  
19 and immersion tin.

1 27. The electronic package of claim 26 wherein said first and said second circuitized  
2 substrates are comprised of a material selected from the group consisting of polyimide,  
3 polytetrafluoroethylene and epoxy glass cloth.

1 28. The electronic package of claim 26 wherein said at least one conductive aperture of  
2 said first circuitized substrate and said at least one conductive aperture of said second circuitized  
3 substrate comprises a hole having a cylindrical shape.

1 29. The electronic package of claim 26 where said solder member is comprised of a high  
2 melt solder alloy having a melting point temperature greater than about 183 degrees Celsius.

1 30. The electronic package of claim 29 wherein said high melt solder alloy is comprised  
2 of metallic material, said metallic material is selected from the group consisting of tin, lead, gold,  
3 silver, antimony, and combinations thereof.

1 31. The electronic package of claim 26 wherein said first contact portion of said solder  
2 member extending from said external surface of said conductive aperture of said first circuitized  
3 substrate forms a connection to a printed circuit board.--

#### REMARKS

The specification is amended to reference the parent application, SN 09/282,842.

Claims 1-25 are cancelled.

New independent claim 26 recites the subject matter of original independent structure claim 1, includes the limitations of original claims 5-8, and includes the patentably distinct limitations of claim 11, namely that the first contact portion of the solder member extending from the external surface of the conductive aperture of the first circuitized substrate includes a cross-sectional configuration that is substantially oval or ellipsoidal.

New dependent claims 27-31 recite the subject matter of original dependent claims 2, 4, 9, 10 and 12, respectively, and depend from new patentably distinct claim 26.

Support for new claims 26-31 is found in the parent application.